This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claim 1 (currently amended): An integrated circuit package~~, having central leads~~ comprising:

a substrate having an upper surface, a lower surface and a long slot penetrating from the upper surface to the lower surface, wherein the lower surface ~~is forming~~ formed with a wiring regions arranged at ~~the two sides~~ one side of the long slot, ~~and~~ the wiring regions ~~is formed forming~~ with a plurality of ~~connected~~ connection points, and a ~~the~~ length of the wiring regions ~~are~~ is smaller than a length of the long slot of the substrate;

a resistant layer~~42~~, which is coated on and in contact with the lower surface~~54~~ of the substrate~~40~~, and is located between the long slot~~56~~ and the wiring region~~58~~, wherein the resistant layer separates the long slot from the wiring region, and a length of the resistant layer is substantially equal to the length of the wiring region;

a glue layer ~~being~~ coated on the upper surface of the substrate and ~~being~~ located at ~~the~~ a periphery of the long slot;

an integrated circuit having a first surface ~~forming~~ formed with a plurality of bonding pads and a second surface, the first surface being adhered to the glue layer, ~~then~~ the bonding pads being exposed from the long slot of the substrate;

a plurality of wires, each of which is arranged within the long slot of the substrate and ~~is~~ electrically connects ~~connected~~ the bonding pad of the integrated circuit to the ~~connected~~ connection point of the substrate; and

a first compound layer ~~being~~ filled within the long slot of the substrate ~~for protecting~~ to protect the ~~each~~ wires.

Claim 2 (cancelled).

Claim 3 (currently amended): The integrated circuit package ~~having central leads~~ according to claim 1, wherein the ~~connected~~ connection points of the lower surface of the substrate ~~is~~ are formed with a ball grid array (BGA).

Claim 4 (currently amended): The integrated circuit package ~~having central leads~~ according to claim 1, ~~wherein~~ further ~~comprises~~ comprising a second compound layer, which ~~is covered on~~ covers the upper surface of the substrate.